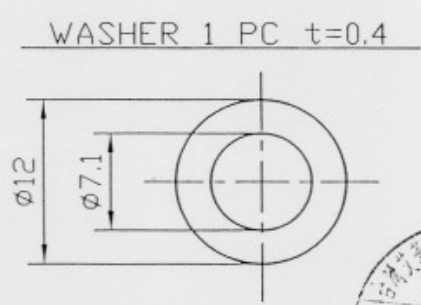
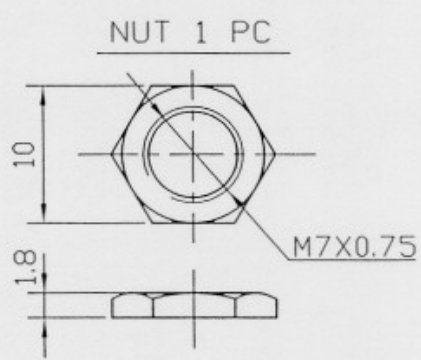


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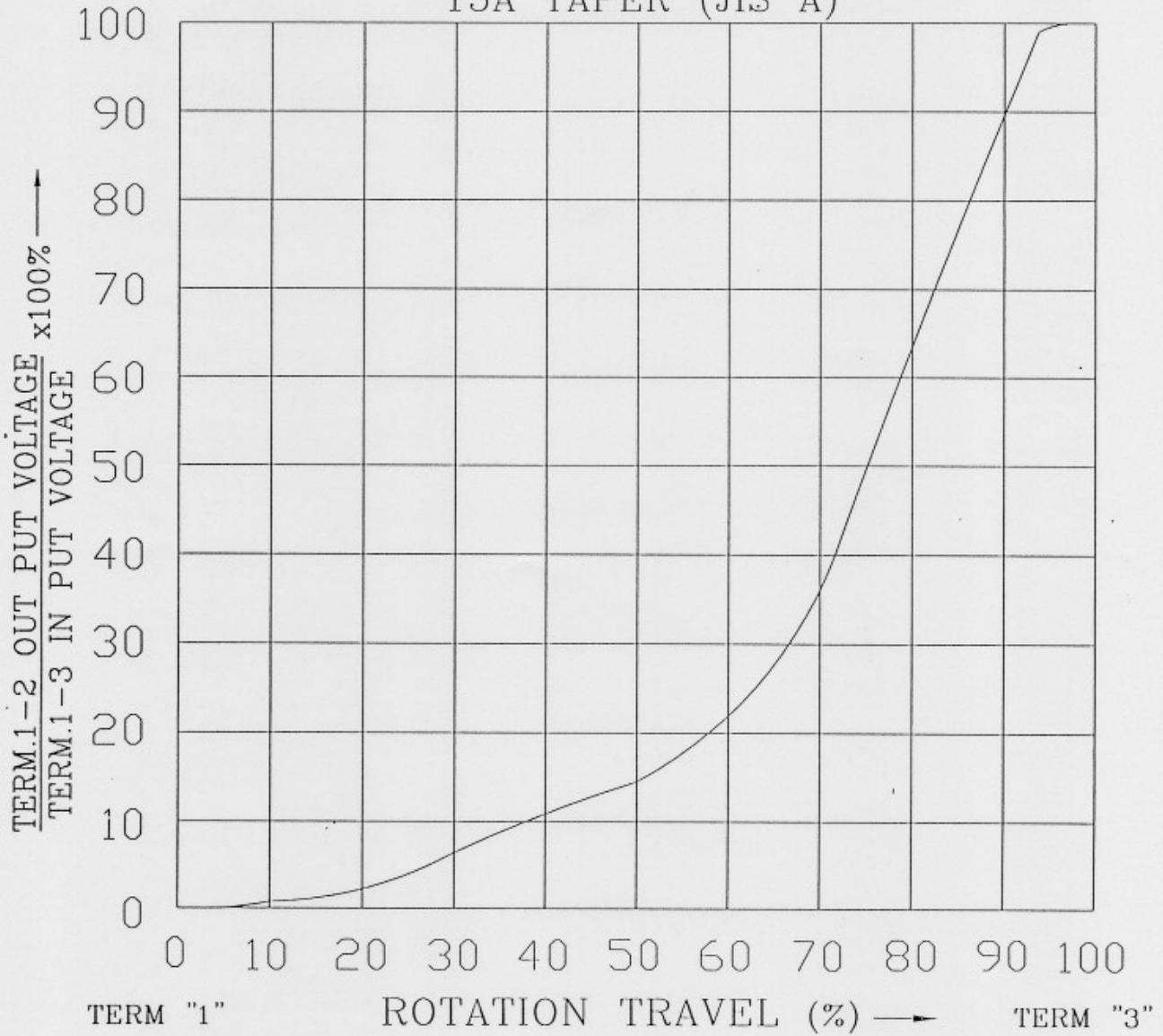


NOTE:
BUSHING MATERIAL IS ZINC ALLOY DIECASTING.

						RV16AF-10-(L)R1-XXX-(0X)	
No.	DATE	DESCRIPTION	PART No.	NAME			
TOL.UNLESS OTHERWISE STATED		DIMENSION	SCALE	DRAWN BY	CHECKED BY	APPROVED BY	DRAWING No.
less than	10	±0.3	2	張月琴	[Signature]	[Signature]	
above	10~30	±0.5					
above	30~100	±1.0	1				
above		±5'					

STANDARD RESISTANCE TAPER

15A TAPER (JIS A)



NO.		DATE	DESCRIPTION		MODEL NAME			
TOL. UNLESS OTHERWISE STATED			DIMENSION	SCALE	DRAWN BY	CHECKED BY	APPROVED BY	DRAWING NO.
less than 10			mm		何 90.8.21 建志	王 90.8.21 茂松	王 90.8.21 茂松	
above 10 ~ 30								
above 30 ~ 100								
above								

TAIWAN ALPHA ELECTRONIC CO., LTD.

Common Specification of Soldering (RoHS-Compliant)

焊接共通規格書

1 Soldering conditions

無鉛銲接條件

Soldering shall be carried out under the following condition:

進行銲接處理時，請確保在下列工作條件：

1-1 Substrate to be soldered: Copper clad laminated phenol board of 1.6mm thick.

銲接物面料：t 1.6 mm 銅箔積層板。

1-2 Specific gravity of flux : 0.82 (applied by foam fluxer).

助銲劑比重：0.82(泡沫型塗佈)。

1-3 Foam head :The foam head should be limited to the height which is half of the board to be soldered .No flux should be allowed to run up onto the board's surface.

泡沫高度：發泡頂端大致在基板厚度一半的位置,而助銲劑不可流入基板表面上。

1-4 Preheating: Surface temperature of the substrate is allowed to be heated up , at most, to 100°C , and sustain at the respective temperature for two minutes as a maximum.

預熱：基板表面溫度 100°C 以下，2 分鐘以內。

1-5 Conventional Soldering: To be performed within 10 seconds at 260°C or below.

一般銲接：260°C 以下，10 秒以內。

(This item is not recommended for and applicable in reflow soldering)

(本項銲錫溫度條件不適用於回流銲接作業設備)

1-6 Manual soldering : To be performed within 3 seconds at 350±5°C

手銲：350±5°C，3 秒以內。

Either items 1-5 or 1-6 should not be carried out more than 2 times.

項目 1-5 一般銲接或 1-6 手銲接不能超過兩回。

The conditions stipulated above are only applicable to conventional soldering but not reflow soldering. If your soldering implementation suggests otherwise , please provide your specific soldering requirement.

以上為一般銲接作業條件(不包括回流銲),使用高溫銲接作業設備請另外提出需求。